

QT-Brightek Chip LED Series

SMD 1208 LED

Part No.: QBLP653 Series

Product: QBLP653_series	Date: November 10, 2016	Page 1 of 14
	Version# 1.7	

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Introduction

Feature:

- Water clear lens
- Package in tap and reel
- Bright 1208 LED package
- InGaN technology for IB/IG/IW
- AllnGaP technology for R/AG/Y/O
- 15° Viewing Angle (R/AG/Y/O/IB/IG)
- 130° Viewing Angle (IW)

Description:

This bright 1208 LEDs have a height profile of 2.5mm. With narrow viewing angle, LED produces high bright light output.

Application:

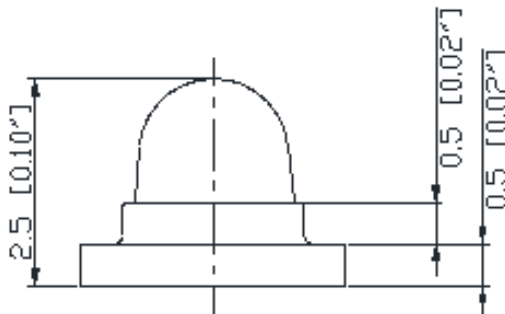
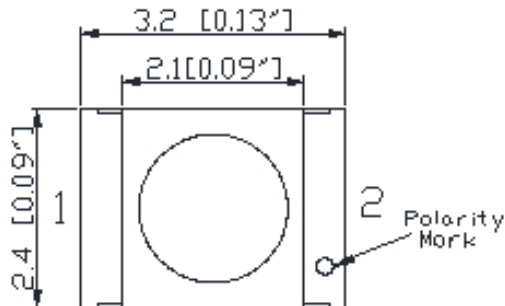
- Status indication
- Back lighting application

Certification & Compliance:

- TS16949
- ISO9001
- RoHS Compliant



Dimension:



Units: mm / tolerance = +/-0.15mm

Electrical / Optical Characteristic (T=25 °C)

Product	Color	I _F (mA)	V _F (V)		λ _D (nm)			I _V (mcd)	
			Typ.	Max.	Min.	Typ.	Max.	Min.	Typ.
QBLP653-IW	White	20	3.1	3.7	X = 0.25 Y = 0.24	X = 0.28 Y = 0.29	X = 0.33 Y = 0.34	100	180
QBLP653-IB	Blue	20	3.2	3.7	455	460	465	400	750
QBLP653-IG	Green	20	3.3	3.7	520	525	530	4000	11000
QBLP653-R	Red	20	2.0	2.5	620	625	630	2000	3850
QBLP653-AG	Yellow Green	20	2.0	2.5	565	570	576	320	620
QBLP653-Y	Yellow	20	2.0	2.5	585	590	595	1600	3400
QBLP653-O	Orange	20	2.0	2.5	600	605	610	1600	3350

Absolute Maximum Rating

Material	P _d (mW)	I _F (mA)	I _{FP} (mA)*	V _R (V)	T _{OP} (°C)	T _{ST} (°C)	T _{SOL} (°C)**
InGaN	111	30	125	5	-40 ~ +80	-40 ~ +85	260
AllnGaP	75	30	125	5	-40 ~ +80	-40 ~ +85	260

*Duty 1/8 @ 1KHz

**IR Reflow for no more than 10 sec @ 260 °C

Forward Voltage V_F for AllnGaP @I_F=20mA

Bin	Min.	Max.	Unit
□	1.7	2.5	V

Forward Voltage V_F for InGaN @I_F=20mA

Bin	Min.	Max.	Unit
f	2.8	3.1	V
g	3.1	3.4	
h	3.4	3.7	

Luminous Intensity I_V @ $I_F=20mA$

Bin	Min.	Max.	Unit
J	100	125	mcd
K	125	160	
L	160	200	
M	200	250	
N	250	320	
O	320	400	
P	400	500	
Q	500	630	
R	630	800	
S	800	1000	
T	1000	1250	
U	1250	1600	
V	1600	2000	
W	2000	2500	
X	2500	3200	
Y	3200	4000	
Z	4000	5200	
a	5200	6800	
b	6800	8800	
c	8800	11200	
d	11200	14200	
e	14200	18000	

Dominant Wavelength λ_D for Blue @ $I_F=20mA$

Bin	Min.	Max.	Unit
C	455	457.5	nm
D	457.5	460	
E	460	462.5	
F	462.5	465	

Dominant Wavelength λ_D for Green @ $I_F=20mA$

Bin	Min.	Max.	Unit
U	520	522.5	nm
V	522.5	525	
W	525	527.5	
X	527.5	530	

Dominant Wavelength λ_D for Red @ $I_F=20mA$

Bin	Min.	Max.	Unit
t	620	625	nm
u	625	630	

Dominant Wavelength λ_D for Yellow Green @ $I_F=20\text{mA}$

Bin	Min.	Max.	Unit
h	565	568	nm
i	568	572	
j	572	576	

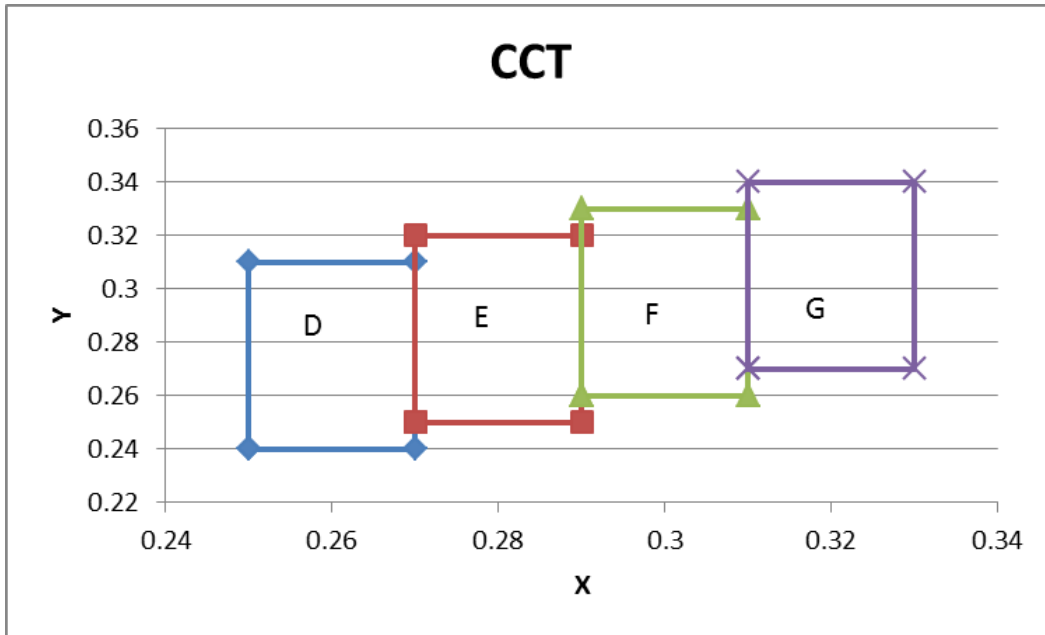
Dominant Wavelength λ_D for Yellow @ $I_F=20\text{mA}$

Bin	Min.	Max.	Unit
m	585	590	nm
n	590	595	

Dominant Wavelength λ_D for Orange @ $I_F=20\text{mA}$

Bin	Min.	Max.	Unit
p	600	605	nm
q	605	610	

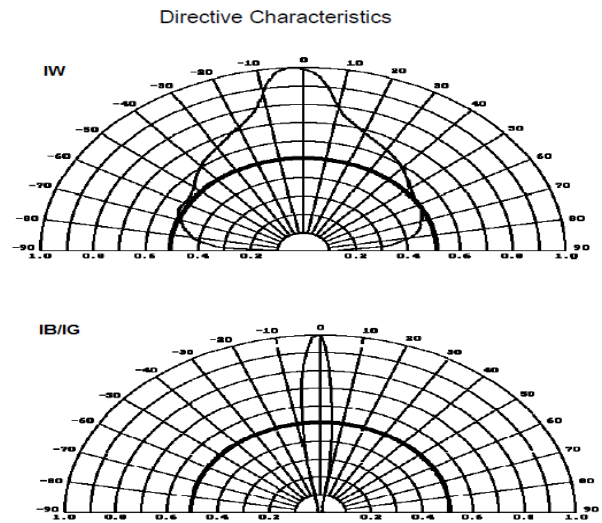
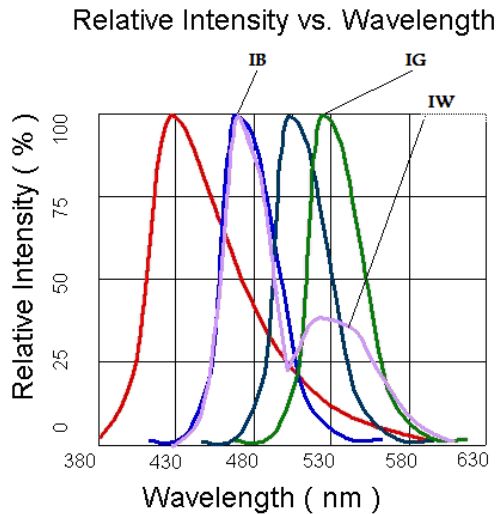
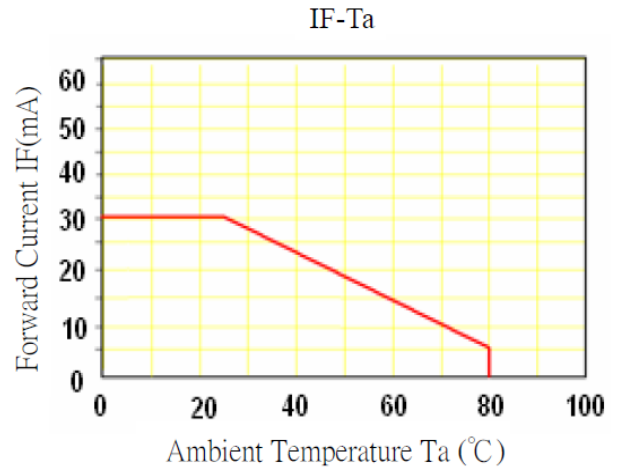
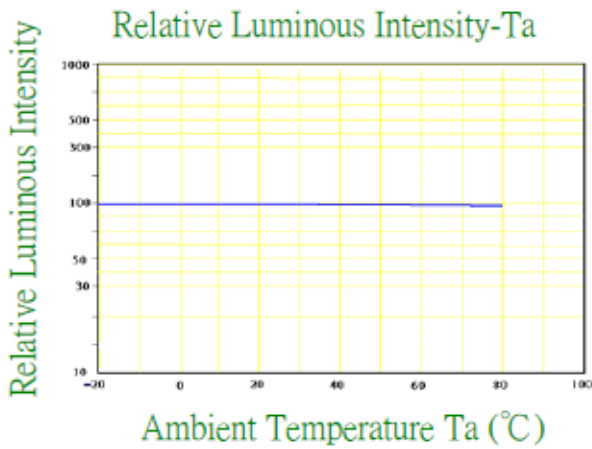
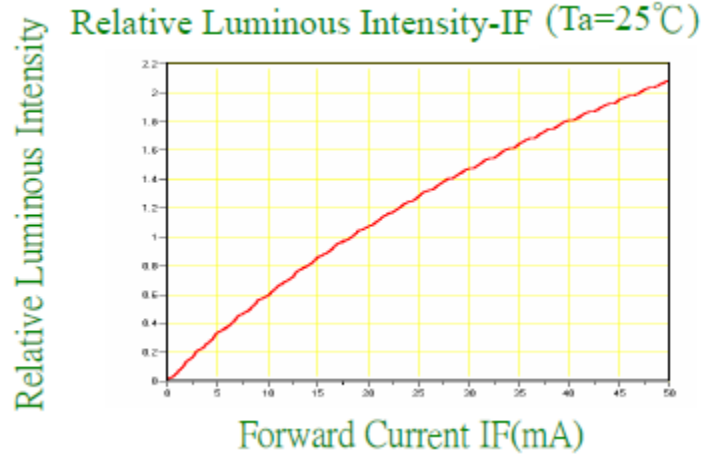
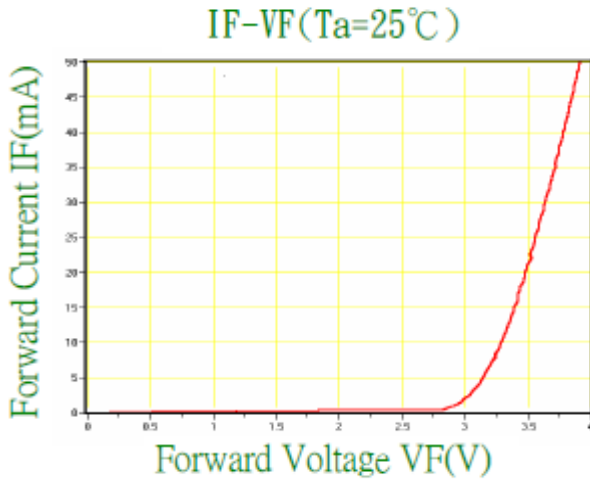
CIE Chromaticity Table



D		E		F		G	
0.25	0.24	0.27	0.25	0.29	0.26	0.31	0.27
0.25	0.31	0.27	0.32	0.29	0.33	0.31	0.34
0.27	0.31	0.29	0.32	0.31	0.33	0.33	0.34
0.27	0.24	0.29	0.25	0.31	0.26	0.33	0.27
0.25	0.24	0.27	0.25	0.29	0.26	0.31	0.27

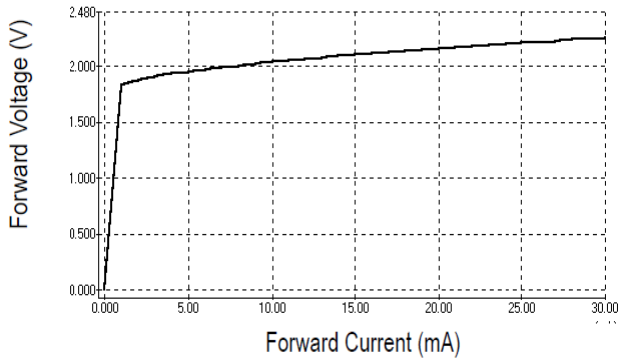
Characteristic Curves

InGaN (IB/IG/IW)

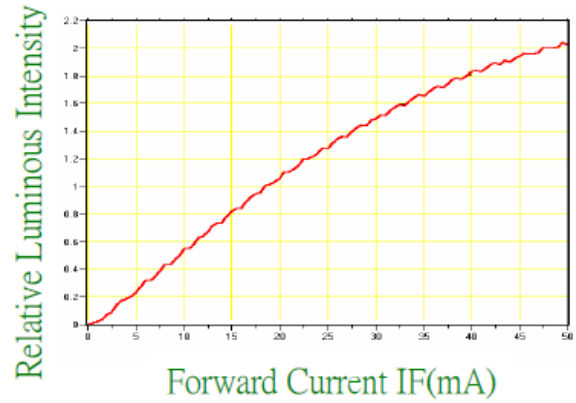


AllInGaP (R/AG/Y/O)

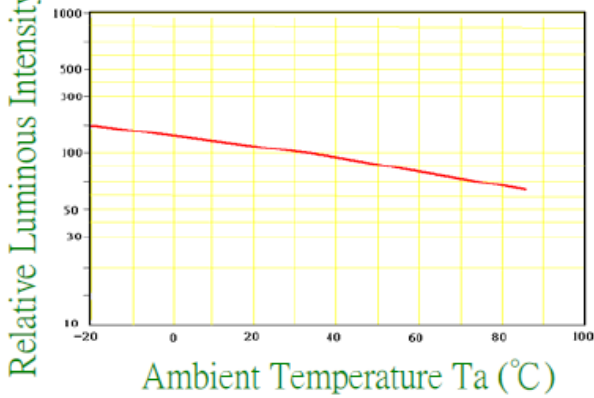
Forward Current vs. Forward Voltage



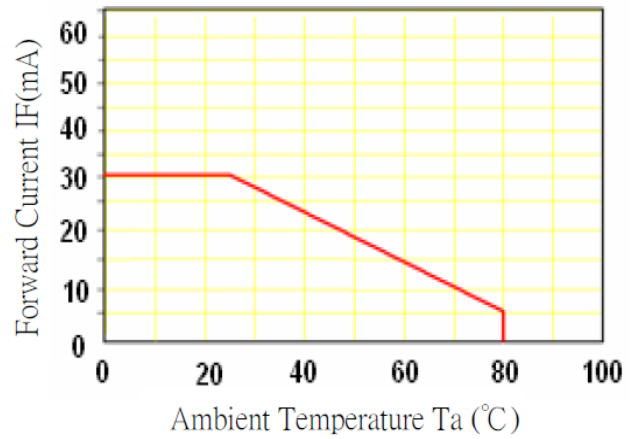
Relative Luminous Intensity-IF (Ta=25°C)



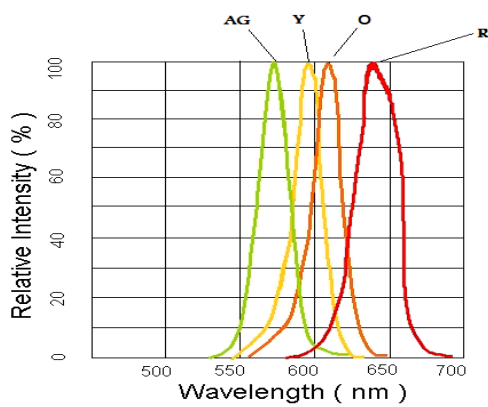
Relative Luminous Intensity-Ta



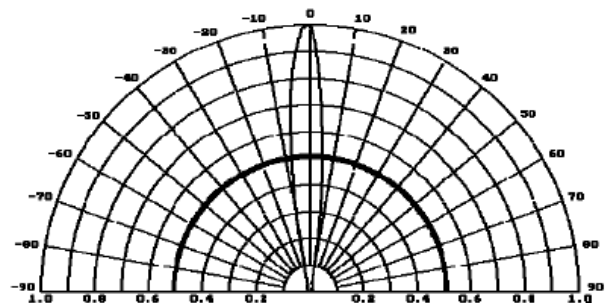
IF-Ta



Relative Intensity vs. Wavelength

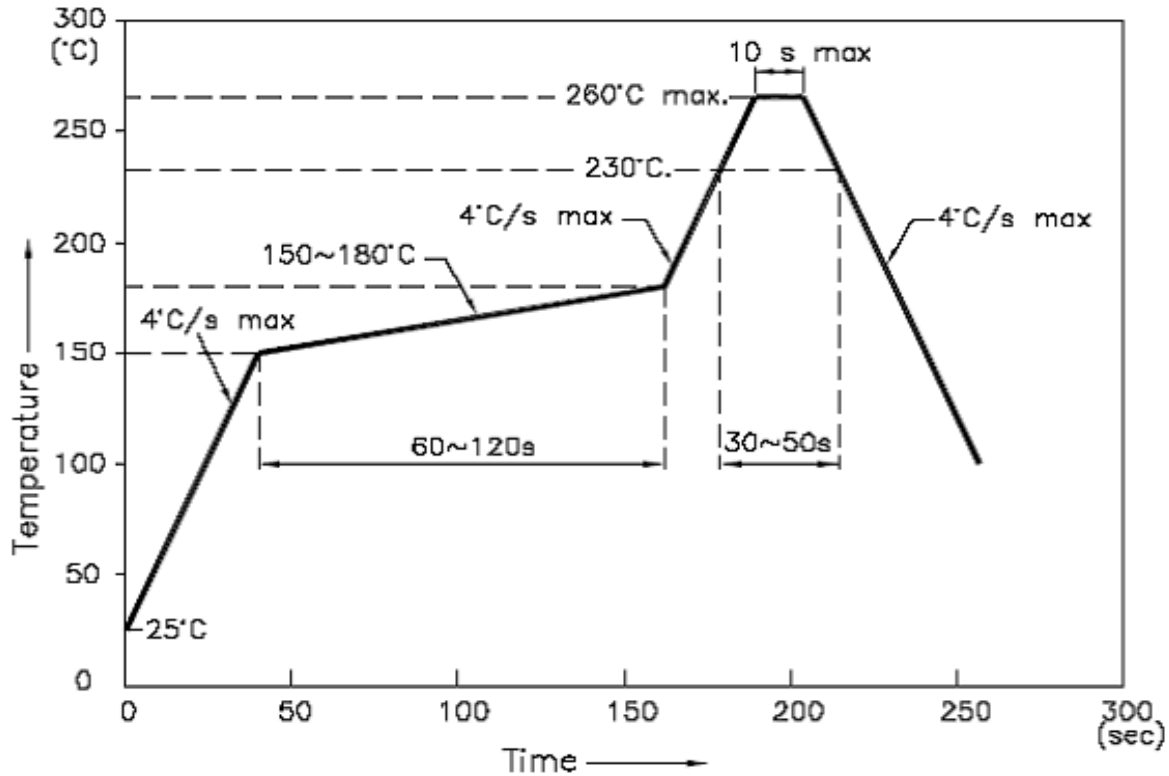


Directive Characteristics

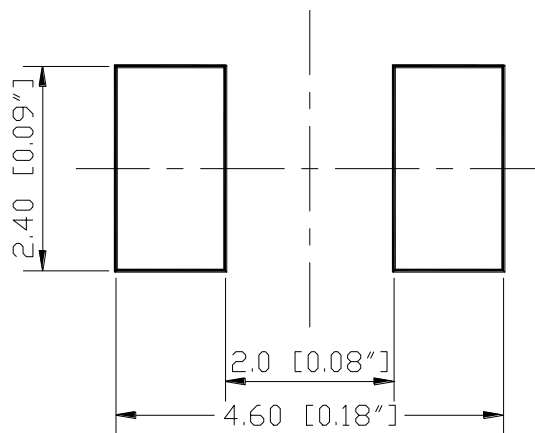


Solder Profile & Footprint

- Recommended tin glue specifications: melting temperature in the range of 178~192 °C
- The recommended reflow soldering profile is as follows (temperatures indicated are as measured on the surface of the LED resin):



Recommended Pad Layout



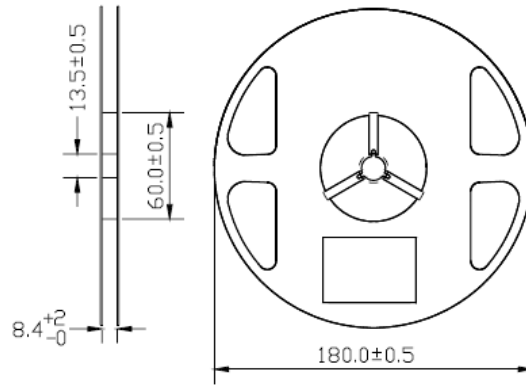
Units: mm

Tolerance: ± 0.1mm

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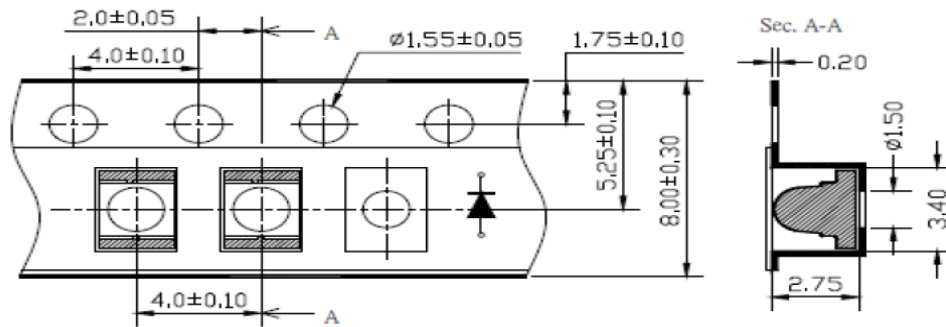
Packing

Reel Dimension:



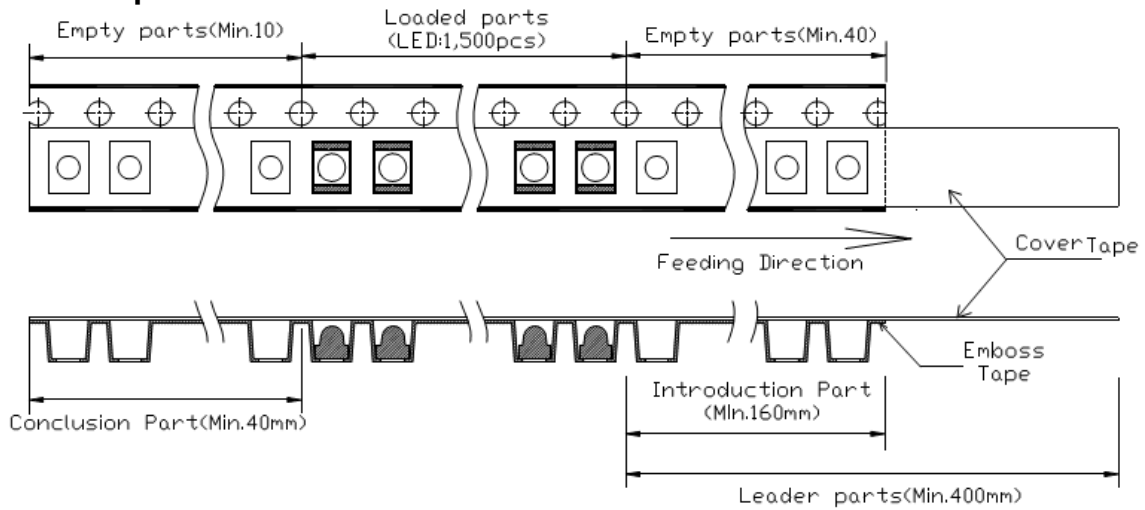
Unit: mm

Tape Dimension:

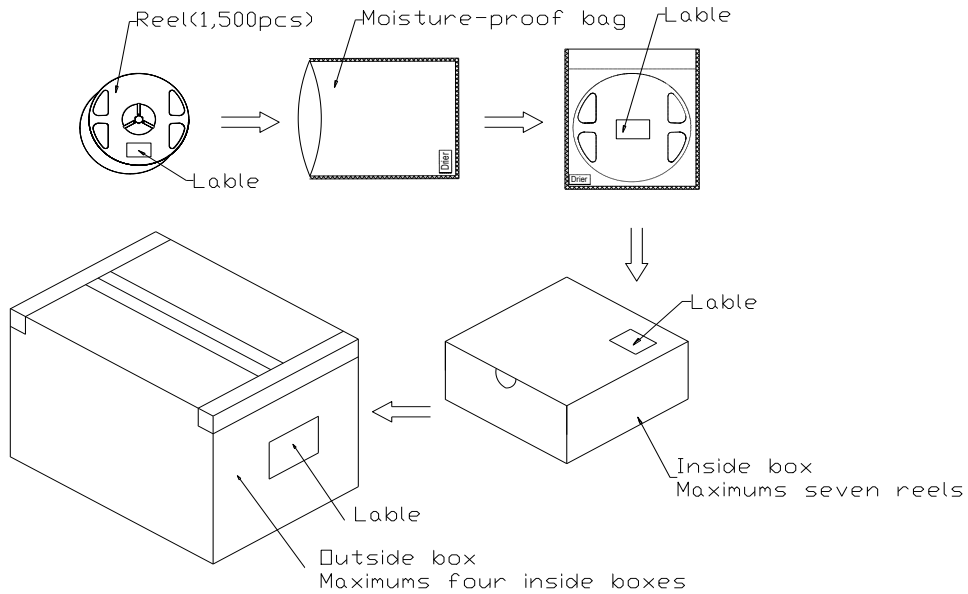


Unit: mm

Arrangement of Tape:



Packaging Specification:



Labeling



Part No: _____

Customer P/N: _____

Item: _____

Q'ty: _____

Vf: _____

Iv: _____

WI: _____

Date: _____

Made in China

Ordering Information

Part #	Orderable Part #	Spec Range	Quantity per reel
QBLP653-IW	QBLP653-IW	Iv=180mcd typ. @ 20mA, / CIE Coordinate: (X=0.28, Y=0.29) typ.	1,500 units
QBLP653-IB	QBLP653-IB	Iv=750mcd typ. / Color=455nm ~ 465nm	1,500 units
QBLP653-IG	QBLP653-IG	Iv=11000mcd typ. / Color=520nm ~ 530nm	1,500 units
QBLP653-R	QBLP653-R	Iv=3850mcd typ. / Color =620nm ~ 630nm	1,500 units
QBLP653-AG	QBLP653-AG	Iv=620mcd typ. / Color=565nm ~ 576nm	1,500 units
QBLP653-Y	QBLP653-Y	Iv=3400mcd typ. / Color =585nm ~ 595nm	1,500 units
QBLP653-O	QBLP653-O	Iv=3350mcd typ. / Color=600nm ~ 610nm	1,500 units

Revision History

Description:	Revision #	Revision Date
New Release of QBLP653_series	V1.0	12/08/2011
Amend Packing Spec	V1.1	12/13/2011
Update Characteristic Curves	V1.2	12/29/2011
Update to new format	V1.3	08/16/2012
Update Iv binning for white	V1.4	02/04/2014
Update Iv binning for IG	V1.5	04/23/2014
Update Iv inning and brightness for IG	V1.6	08/26/2016
Minor update on package drawing appearance	V1.7	11/10/2016

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